

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	198	219/121.39.ccls.	USPAT	OR	ON	2005/03/29 15:46
L2	179	1 and plasma	USPAT	OR	ON	2005/03/29 15:37
L3	8	2 and (etch\$3)	USPAT	OR	ON	2005/03/29 15:37
L5	170	1 and (plasma with (cut\$4 or etch\$3 or dic\$3 or separating or separation or separate or separated))	USPAT	OR	ON	2005/03/29 15:39
L6	48	5 and (high adj frequency)	USPAT	OR	ON	2005/03/29 15:40
S1	4	((("5693182") or ("5824595") or ("6013534") or ("6239036"))).PN.	USPAT	OR	OFF	2005/03/28 17:55
S2	1242	438/460.ccls. or 438/462.ccls. or 438/463.ccls. or 438/464.ccls.	USPAT	OR	ON	2005/03/28 17:56
S3	253	S2 and plasma	USPAT	OR	ON	2005/03/28 17:57
S4	173	S2 and (plasma with (separation or separating or separates or separated or cut or cutting or cuts or dice or dicing or dices or diced or etch or etching or etches or etched or etchant))	USPAT	OR	ON	2005/03/28 18:53
S5	103744	plasma with (separation or separating or separates or separated or cut or cutting or cuts or dice or dicing or dices or diced or etch or etching or etches or etched or etchant)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/28 18:54
S6	13189	S5 and (semiconductor adj wafer)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/28 18:54
S7	2366	S6 and (silicon and fluorine)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/28 18:54
S8	416	S7 and (etch adj stop)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/28 18:55

S9	415	S8 not S4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/28 18:56
S10	1	S9 and (plasma adj dic\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/28 18:57
S11	324	S9 and (plasma adj etch\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/28 19:22